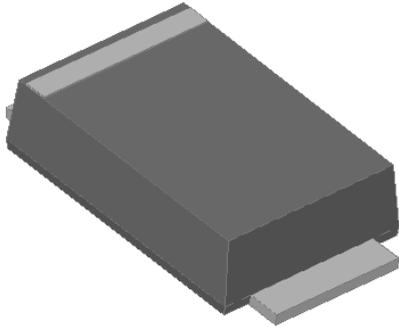


Surface Mount Super Fast Recovery Rectifier

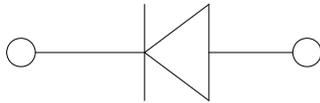


Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Super Fast reverse recovery time
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in high frequency rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.



Mechanical Data

- **Package:** SMAF
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■ Maximum Ratings (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	E3GF
Device marking code			E3GF
Repetitive peak reverse voltage	V _{RRM}	V	400
Average rectified output current @60Hz half-sine wave, resistance load, TL (Fig.1)	I _O	A	3.0
Surge(non-repetitive)forward current @60Hz half-sine wave,1 cycle, T _a =25°C	I _{FSM}	A	70
Storage temperature	T _{stg}	°C	-55~+150
Junction temperature	T _j	°C	-55~+150

■ Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	E3GF
Maximum instantaneous forward voltage drop per diode	V _F	V	I _{FM} =3.0A	1.3
Maximum reverse recovery time	t _r	ns	I _F =0.5A, I _R =1.0A, I _r =0.25A	35
Maximum DC reverse current at rated DC blocking voltage per diode @ V _{RM} =V _{RRM}	I _{RRM}	μA	T _a =25°C	5.0
			T _a =125°C	100



■ Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	E3GF
Typical Thermal resistance	R _{θJ-A} ⁽¹⁾	°C/W	75
	R _{θJ-L} ⁽¹⁾		20

Note:
 (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

■ Characteristics (Typical)

FIG1: I_o-TL Curve

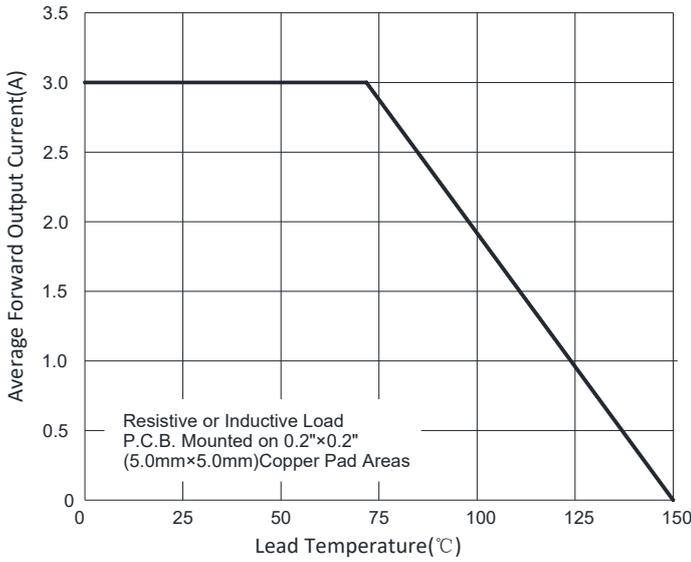


FIG2: Surge Forward Current Capability

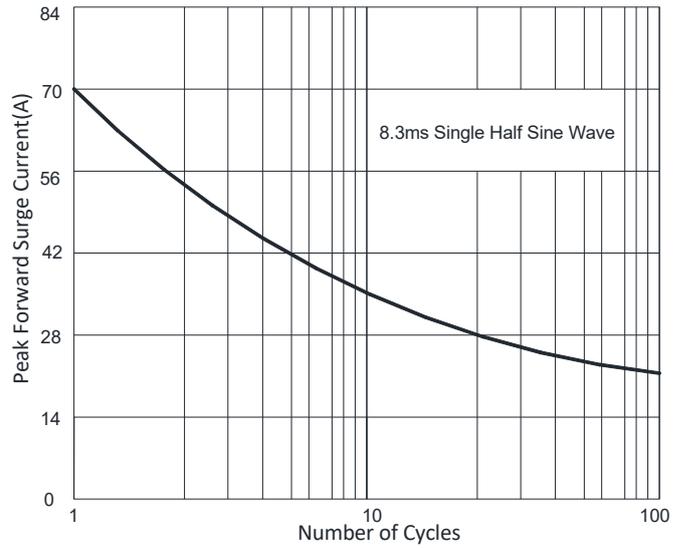


FIG3: Typical Forward Voltage

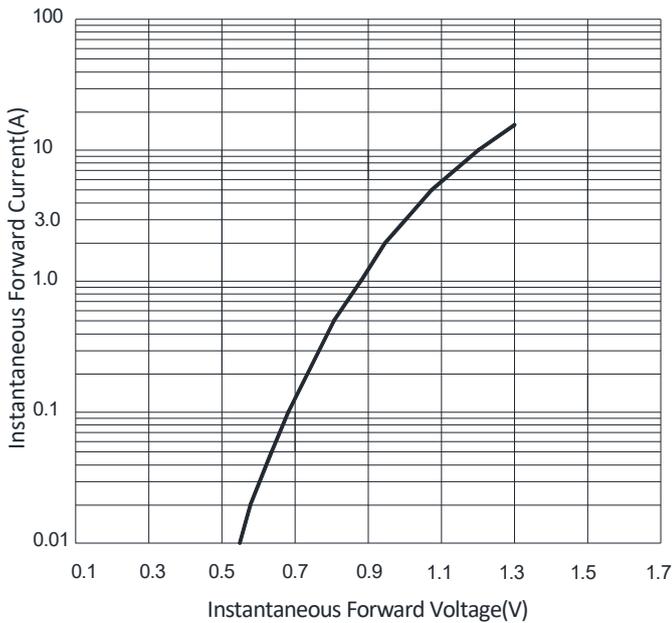


FIG4: Typical Reverse Characteristics

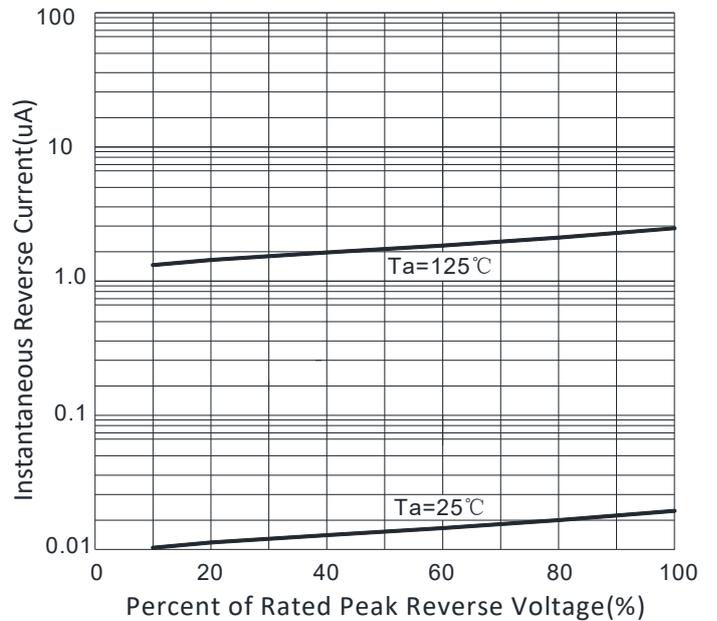
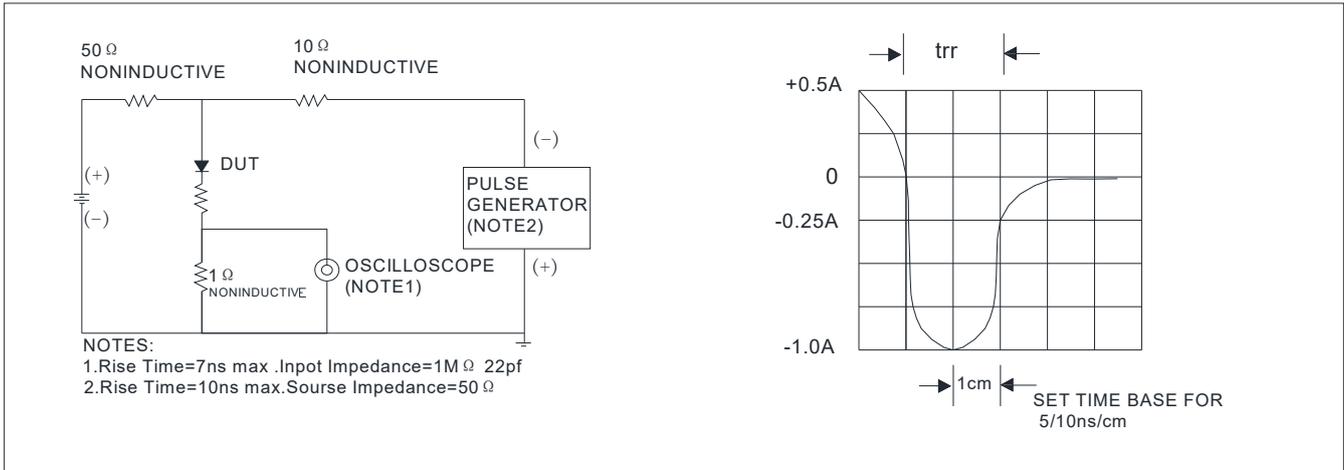


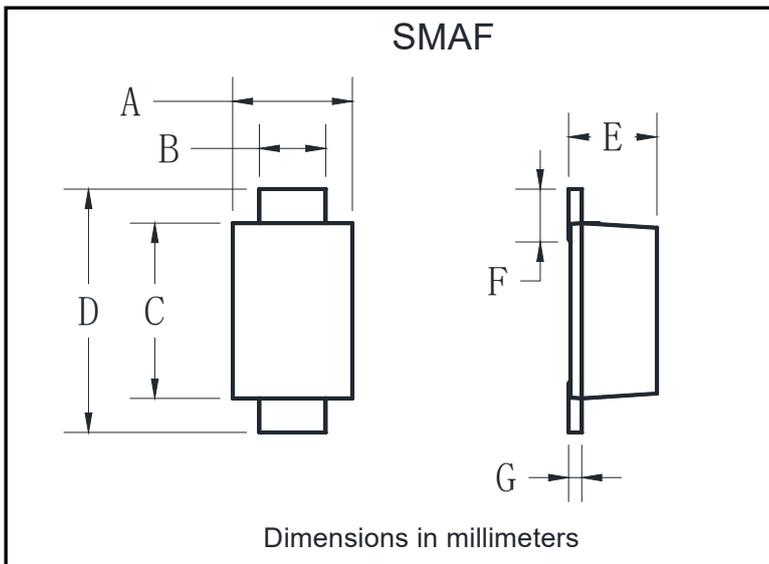
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



Ordering Information (Example)

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
E3GF	F1	Approximate 0.034	3000	12000	96000	7" reel
E3GF	F2	Approximate 0.034	10000	20000	160000	13" reel
E3GF	F3	Approximate 0.034	10000	20000	120000	13" reel
E3GF	F4	Approximate 0.034	7500	15000	120000	13" reel

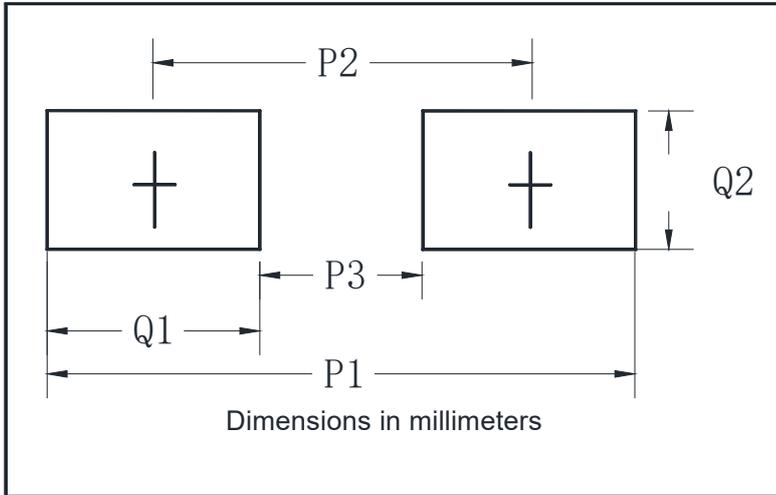
Outline Dimensions



SMAF		
Dim	Min	Max
A	2.40	2.80
B	1.35	1.45
C	3.40	3.60
D	4.40	4.80
E	1.05	1.25
F	0.50	1.00
G	0.15	0.22



■ Suggested pad layout



SMAF	
Dim	Millimeters
P1	6.50
P2	4.00
P3	1.50
Q1	2.50
Q2	1.70



E3GF

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